



SOD132

Hermetically sealed plastic package; SMB; 2 leads

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SOD132
Package type industry code	SOD132
Package style descriptive code	SOD (small outline diode)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	SMB. DO-214AA
Mounting method type	S (surface mount)
Issue date	20-3-2013

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		3.3	-	3.6	3.95	mm
E	package width		4.05	-	4.3	4.6	mm
A	seated height		1.9	-	2.2	2.45	mm
n ₂	actual quantity of termination		-	-	2	-	



2. Package outline

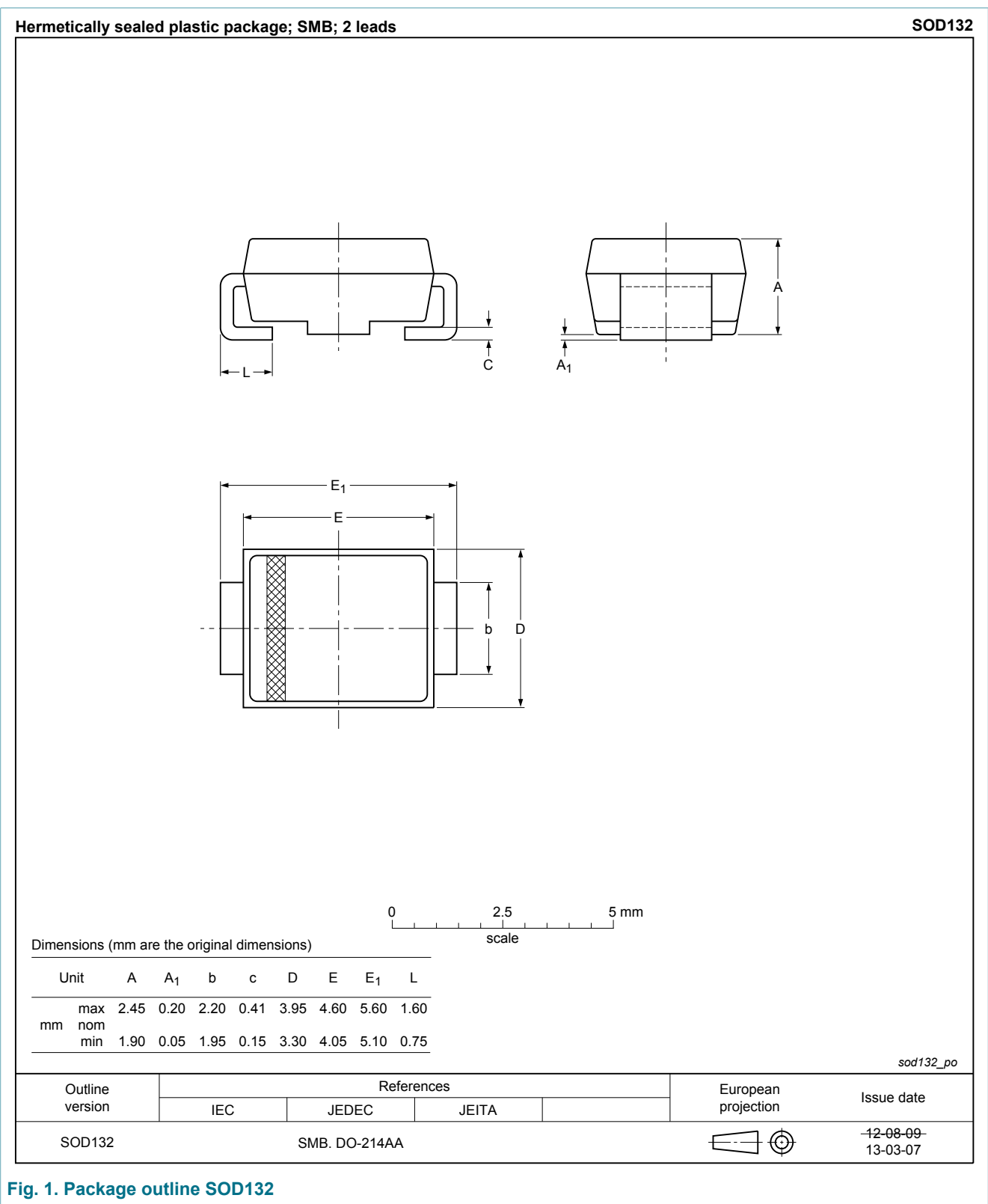


Fig. 1. Package outline SOD132

3. Legal information

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Date of release: 8 February 2016